










PCN Number:		20190410000.1		PCN Date:		Apr 11, 2019																						
Title:		Qualification of RFAB and DMOS6 as an additional Wafer Fab Site options for select devices in LBC8 Technology																										
Customer Contact:		PCN Manager		Dept:		Quality Services																						
Proposed 1st Ship Date:		Jul 11, 2019		Estimated Sample Availability:		Date provided at sample request.																						
Change Type:																												
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials																							
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																							
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																							
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																							
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																							
		<input type="checkbox"/>	Part number change																									
PCN Details																												
Description of Change:																												
Texas Instruments is pleased to announce the qualification of its RFAB and DMOS6 fabrication facilities as an additional Wafer Fab sources for the selected devices listed in "Product Affected" section.																												
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Qual details are provided in the Qual Data Section.																												
Reason for Change:																												
Continuity of Supply																												
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																												
None																												
Changes to product identification resulting from this PCN:																												
Current																												
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Product Affected Group:																												
TMP461AIRUNR		TMP461AIRUNT																										

Qualification Report

Approve Date 26-Mar-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TMP461AIRUN	QBS Product Reference TMP461AIRUN	QBS Process Reference: PCD3215B00BZQZR/ PCD3215B00DZQZR
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	1/77/0	-	-
HBM	ESD - HBM	2000 V	1/3/0	1/3/0	-
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	-
HTOL	Life Test, 125C	1000 Hours	1/77/0	-	2/154/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	1/77/0	-	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	2/154/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	-
PD	Physical Dimensions	Per mechanical drawing	-	3/45/0	-
SD	Solderability	Pb Free	-	3/66/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	1/77/0	3/231/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
 Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com